



IRPS 2017 Technical Program Committee Members

Committee	Role	First Name	Last Name	Affiliation
3D/2.5D/Packaging	Chair	Alan	Lucero	Intel
	Vice-Chair	Sudarshan	Rangaraj	Amazon Lab 126
		Andy	Bao	Qualcom
		David	Huitink	Univ. of Arkansas
		Alan	Lucero	Intel
		Pradyumna	Prabhumirashi	Apple
		Sudarshan	Rangaraj	Amazon Lab 126
		Richard	Rao	Microsemi
Circuit Reliability/Aging	Chair	Vijay	Reddy	Texas Instruments
	Vice-Chair	Chris	Kim	University of Minnesota
		David	Burnett	GlobalFoundries
		Florian	Cacho	STMicroelectronics
		Kevin	Cao	ASU
		Vikas	Chandra	ARM
		Karl	Hofmann	Infineon
		Chris	Kim	University of Minnesota
		Georgios	Konstadinidis	Oracle
		Haldun	Kufluoglu	Qualcomm
		Pong-Fei	Lu	IBM
		Jim	Tschanz	Intel
		Dielectrics - Gate, MOL, BEOL	Co-Chair	Yung-Hei
Co-Chair	Nagarajan		Raghavan	Singapore University of Technology and Design
	Ra		Chanta	IBM
	Lin		Cong	NVidia
	Martin		Gall	Fraunhofer Institute
	Ru		Huang	Peking University
	James		Lloyd	SUNY Poly
	Maria		Luque	Samsung



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Dielectrics - Gate, MOL, BEOL (continued)		Enrique	Miranda	UAB
		Paul	Nicollian	Semiconductor Reliability
		Chetan	Prasad	Intel
		Francesco Maria	Puglisi	Unimore
		Naohito	Suzumura	Renesas
		Christophe	Vallee	CEA
		Bonnie	Weir	Avago
		Shnji	Yokogawa	UEC
ESD/Latchup	Chair	Farzan	Farbiz	Texas Instruments
	Vice-Chair	Michael	Khazhinsky	SI Labs
		Zhong	Chen	University of Arkansas
		Kai	Esmark	Infineon
		Nathan	Jack	Intel
		Mujahid	Muhammad	GlobalFoundries
		Nicolas	Nolhier	Laboratoire d'analyse et d'architecture des systèmes
		Guido	Notermans	NXP
		Moto	Okushima	Renesas
		Alan	Righter	Analog Devices
		Mayank	Shrivastava	Indian Institute of Science
Failure Analysis/Process Integration	Chair	Bryan	Tracy	EAG Laboratories
	Vice-Chair	Kevin	Johnson	Intel
Metallization Reliability	Chair	Ki-Don	Lee	Samsung
	Vice-Chair	Gavin	Hall	ON Semi
		Linjun	Cao	GlobalFoundries
		Howard	Gan	SMIC
		Gavin	Hall	ON Semiconductor
		Ki-Don	Lee	Samsung
		Baozhen	Li	IBM



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Metallization Reliability (continued)		Ming-Hsien	Lin	TSMC
		Cher Ming	Tan	Chang Gung University, Taiwan
		Zsolt	Tokei	IMEC
		Feng	Xia	Intel
Photovoltaics	Chair	Andrea	Cester	University of Padova
	Vice-Chair	Michael	Daenen	Hasselt University
		Fernando A.	Castro	National Physical Laboratory
		Andrea	Cester	University of Padova
		Michael	Daenen	Hasselt University
		Cosimo	Gerardi	Enel Green Power S.p.A., 3Sun
		Suren	Gevorgyan	DTU Energy, Technical University of Denmark
		Salvatore	Lombardo	CNR-IMM, Italy
		Eszter	Voroshazi	IMEC, Belgium
		Martin	Weis	Institute of Electronics and Photonics, Slovak University of Technology
		Karl-Anders	Weiß	Fraunhofer-Institut für Solare Energiesysteme ISE
Product/Memory	Chair	Brian	Pedersen	Intel
	Vice-Chair	Alessandro	Spinelli	Politecnico di Milano
		John	Agness	Rohm Semiconductor
		Jae-Gyung	Ahn	Xilinx
		Marc	Aoulaiche	Micron
		Pierre Chor-Fung	Chia	Cisco
		Eric (Ming-Hsiu)	Lee	Macronix
		Brian	Pedersen	Intel
		Luca	Perniola	CEA
		Nagarajan	Raghavan	Singapore University of Technology and Design
		Richard	Rao	Microsemi
Aamer	Shaukat	Freescale		



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Product/Memory (continued)		Alessandro	Spinelli	Politecnico di Milano
		Peng	Su	Juniper
		Jan	Van Houdt	IMEC
		Cristian	Zambelli	University of Ferrara
Reliability Testing	Chair	Hosain	Farr	Qualitau
	Vice-Chair	Pascal	Salome	Serma Technologies
		Hosain	Farr	Qualitau
		Kevin	Manning	Analog Devices
		Stéphane	Moreau	CEA-Leti
		Fiorella	Pozzobon	STMicroelectronics
		Dirk	Rudolph	GlobalFoundries
		Pascal	Salome	Serma Tehnologies
Soft Error	Chair	Balaji	Narasimham	Broadcom
	Vice-Chair	Marta	Bagatin	University of Padova
		Thiago	Assis	RCI
		Marta	Bagatin	University of Padova
		Bharat	Bhuva	Vanderbilt
		Indranil	Chaterjee	Airbus
		Mike	Dion	Rockwell Collins
		Adrian	Evans	iRoC
		Yi-Pin	Fanga	TSMC
		Christopher	Frost	Rutherford Appleton Laboratory
		Gilles	Gasiot	STMicroelectronics
		Shah	Jahinuzzaman	Intel
		Michael	King	Sandia Labs
		Nihaar	Mahatme	NXP
		Balaji	Narasimham	Broadcom
	Phil	Oldiges	IBM	



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Committee	Role	First Name	Last Name	Affiliation
Soft Error (continued)		Heather	Quinn	LANL
		Taiki	Uemura	Samsung
		Shi-Jie	Wen	Cisco
System Reliability	Chair	Ajay	Kamath	Google
	Vice-Chair	Guneet	Sethi	Amazon Lab 126
		Randy	Crutchfield	Medtronic
		Aamir	Kazi	Dell
		Amit	Marathe	Google
		Raj	Pendse	Qualcomm
		Shalabh	Tandon	Intel
Transistors/Beyond CMOS	Chair	Souvik	Mahapatra	India Institute of Technology
	Vice-Chair	Steve	Ramey	Intel
		Jason	Campbell	NIST
		Chris	Changze Liu	Samsung
		Suman	Datta	Norte Dame
		Xavier	Federspiel	STMicroelectronics
		Jacopo	Franco	IMEC
		Dawei	Heh	TSMC
		Eric	Pop	Stanford
		Nagarajan	Raghavan	SUTD
		Guido	Sasse	NXP
		Motoyuki	Sato	Toshiba
		Purushothaman	Srinivasan	Globalfoundries
		Stanislav	Tyaginov	TU Wien
		Dhanoop	Varghese	Texas Instruments
	Miaomiao	Wang	IBM	
Wide Band Gap	Chair	Denis	Marcon	IMEC
	Vice-Chair	Sandeep	Bahl	Texas Instruments



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Wide Band Gap (continued)		Kenichiro	Andrew Barnes	ESA
		Sandeep	Bahl	Texas Instruments
		Partha Sarathi	Chakraborty	NXP Semiconductors
		Jose	Jimenez	Qorvo
		Robert	Kaplar	Sandia National Laboratories
		Sameh	Khali	Infineon
		Martin	Kuball	University of Bristol
		Ferdinando	Lucolano	STMicroelectronics
		Denis	Marcon	IMEC
		Matteo	Meneghini	University of Padova
		Peter	Moens	ON Semiconductor
		David	Sheridan	Alpha and Omega Semiconductor
		Kenichiro	Tanaka	Panasonic Corporation